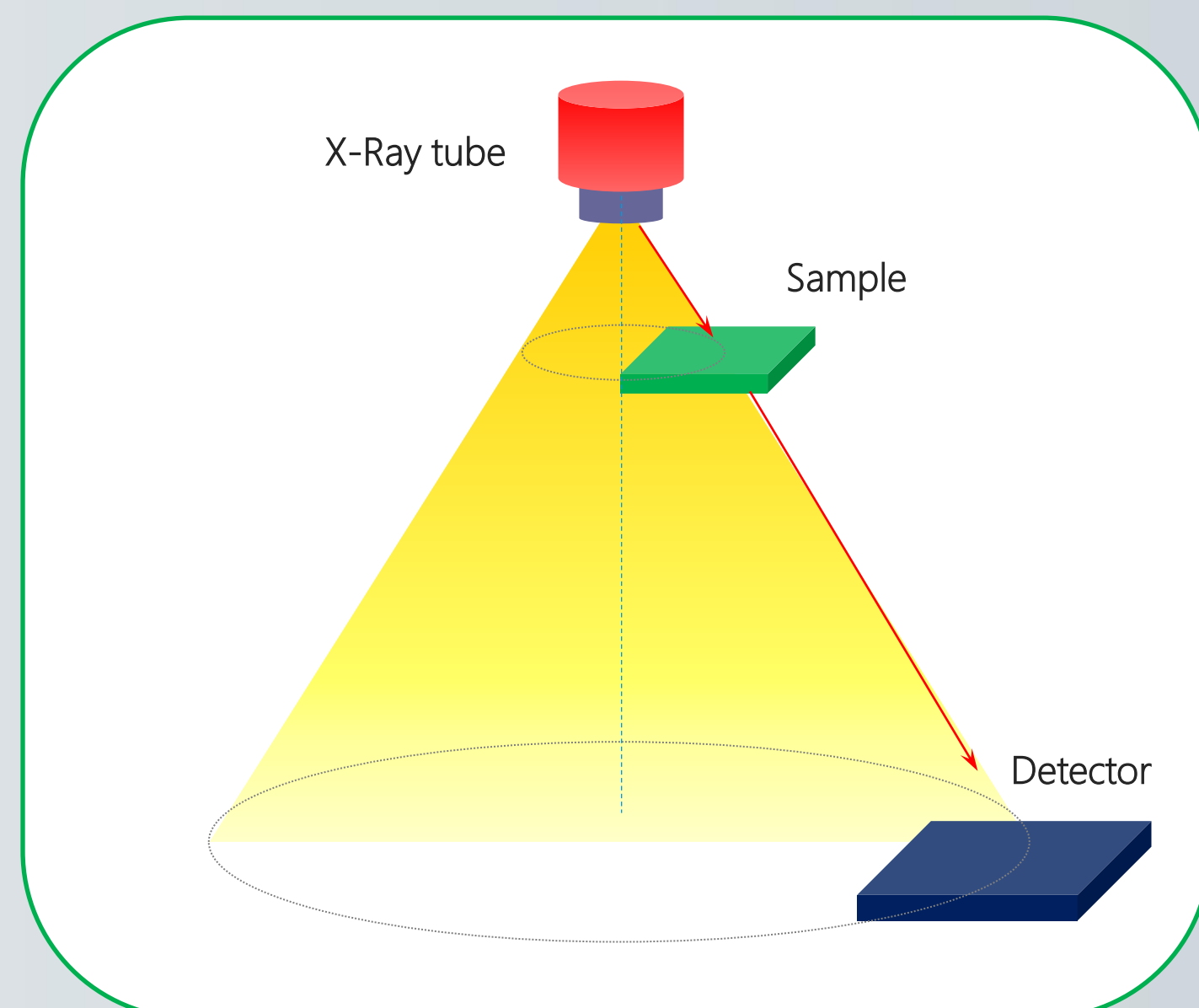




高精度且高效率管理高多层板中的Backdrill加工品质。
透过CT检测技术，以非破坏方法将通孔残铜(Stub)或钻孔深度、孔径等可视化，
实现制造制程的最佳化及良率提升。

Precisely and efficiently manage the backdrill quality in high-layer PCB manufacturing.
CT inspection technology visualizes stub length, drill depth, and hole diameter non-destructively,
enabling process optimization and improved production yield.

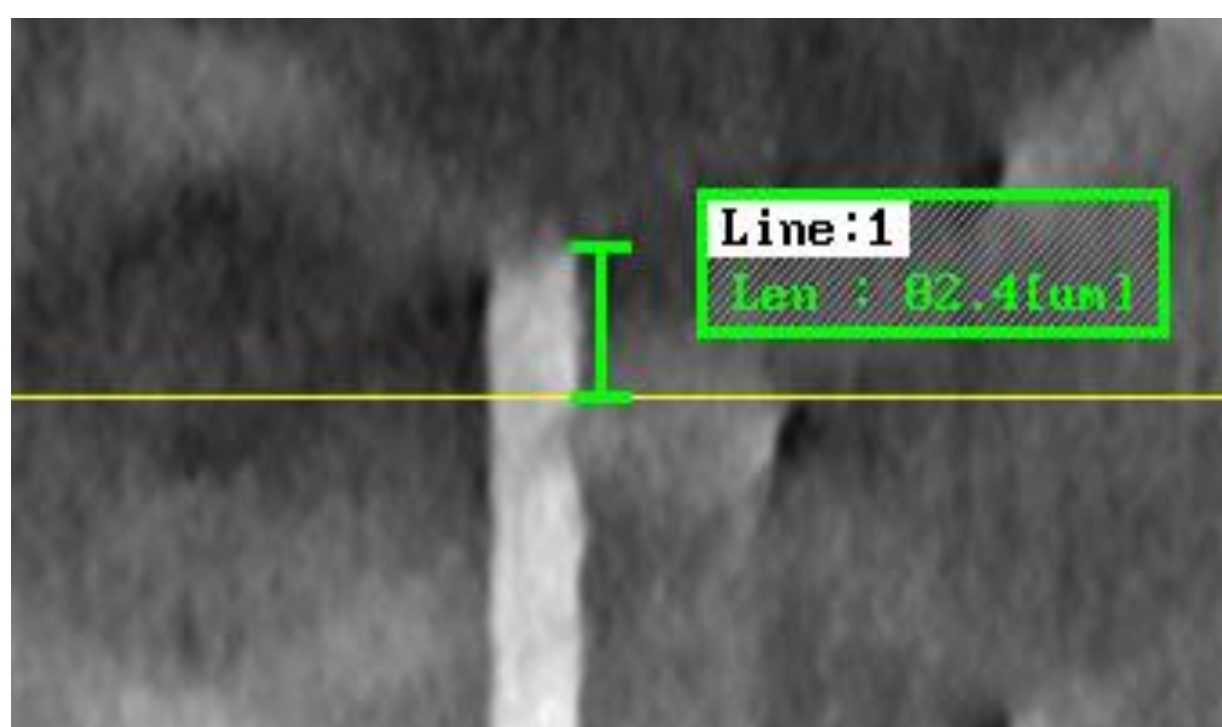
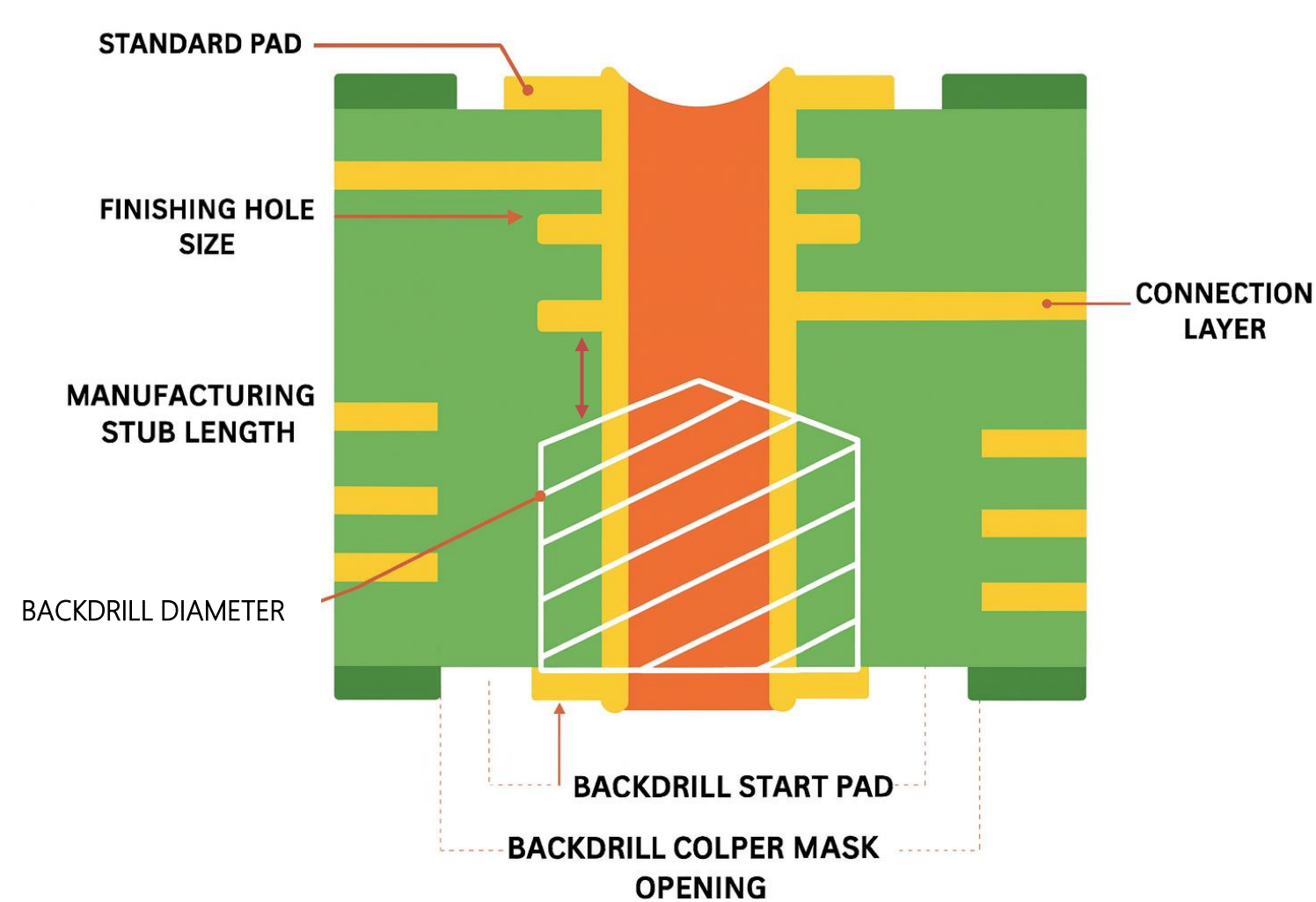
次微米精度、大幅度缩短CT扫描时间
Sub-micron precision with dramatically shorter CT scan time

自动测量Stub长度、及时输出结果数据
Auto stub length measurement — instant data export

实现手把连接即时操作
Real-time control via direct joystick-to-PLC connection

密封型X光管免维护、使用成本低
Sealed X-ray tube, maintenance-free and cost-efficient

检测案例：PCB 制造中的背钻 | Backdrilling in PCB Manufacturing



※本画面仅供参考，可能无预告进行变更。
The user interface is for reference and subject to change without notice.